

FIG.1  
background art

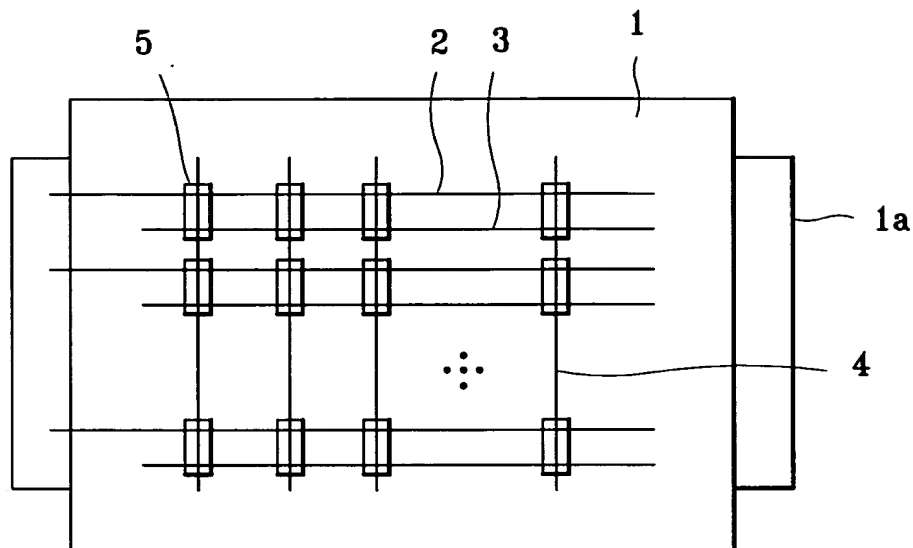
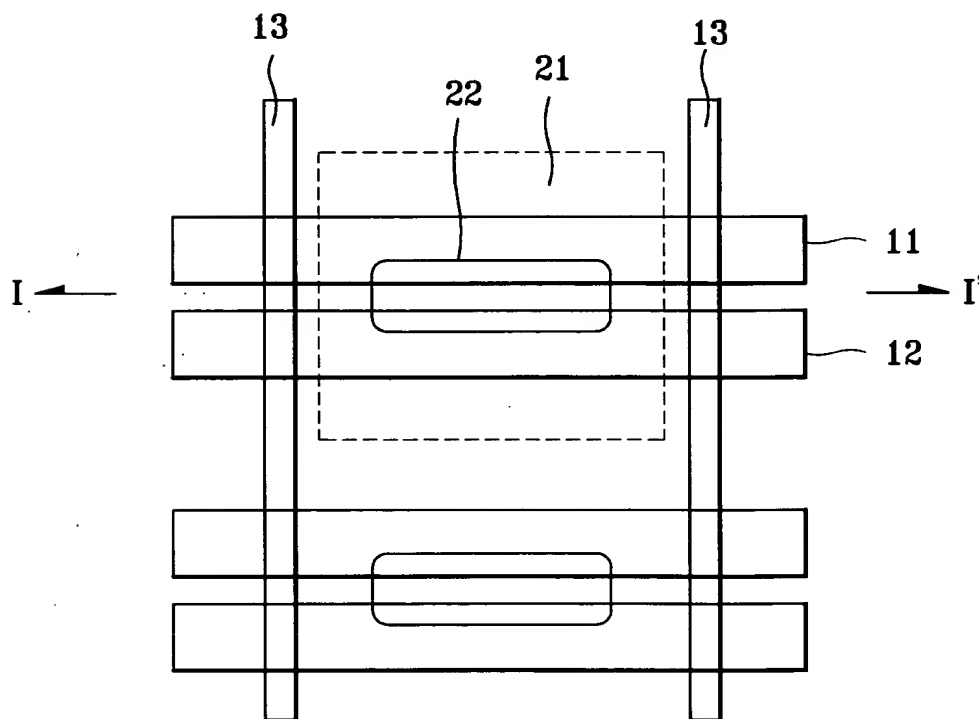


FIG.2a  
background art



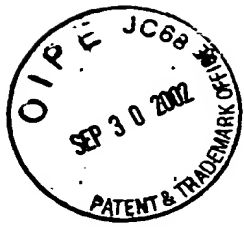


FIG.2b  
background art

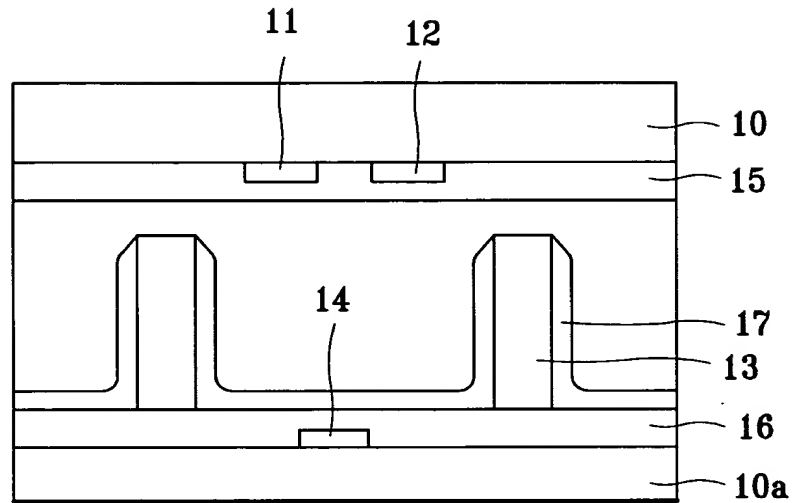


FIG.3  
background art

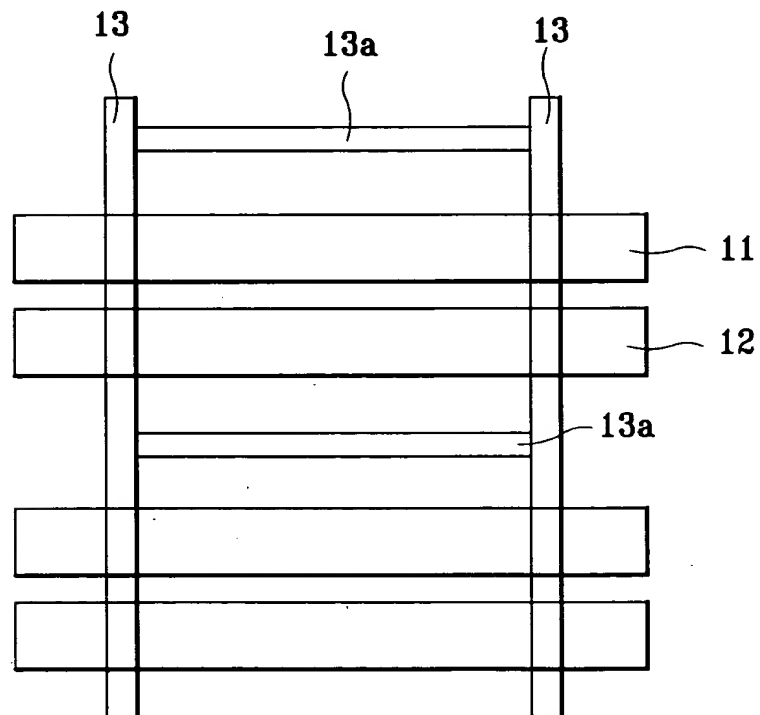


FIG.4a

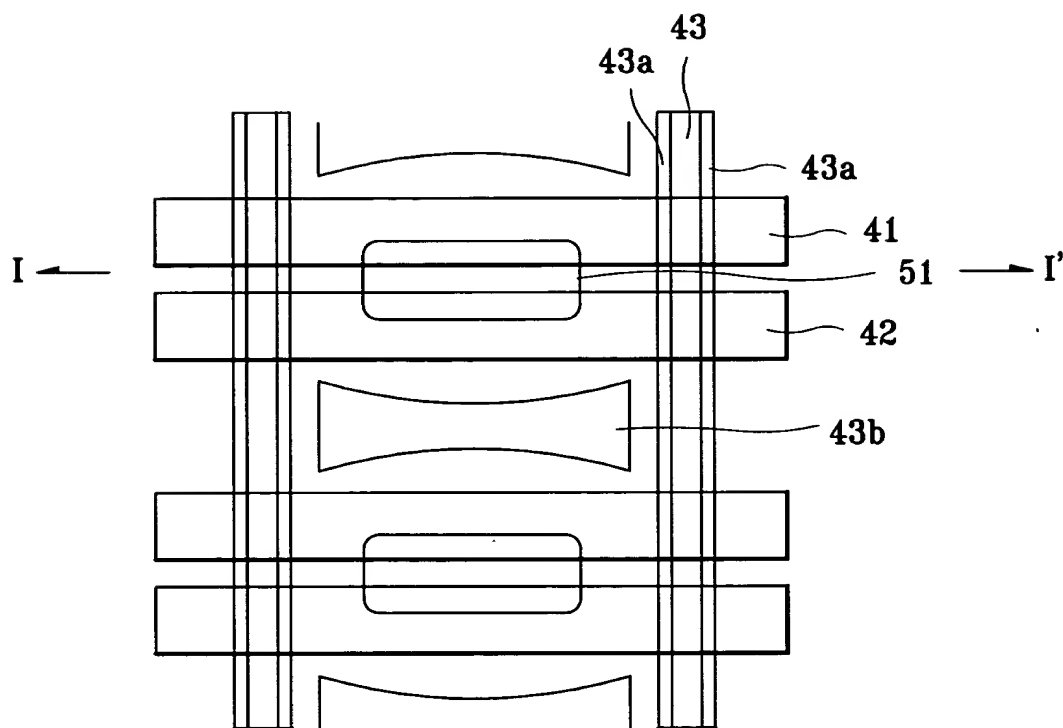


FIG.4b

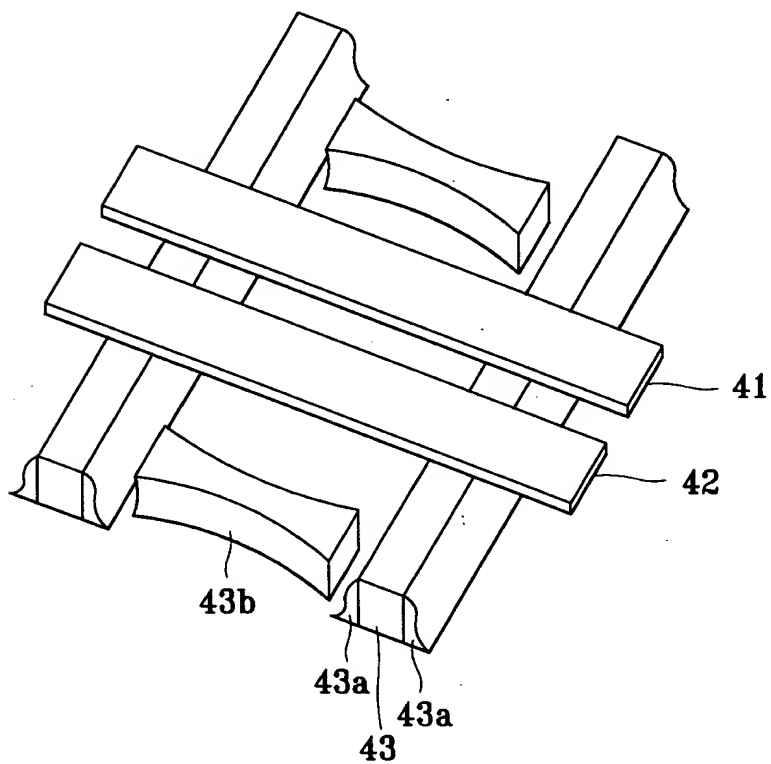


FIG.5

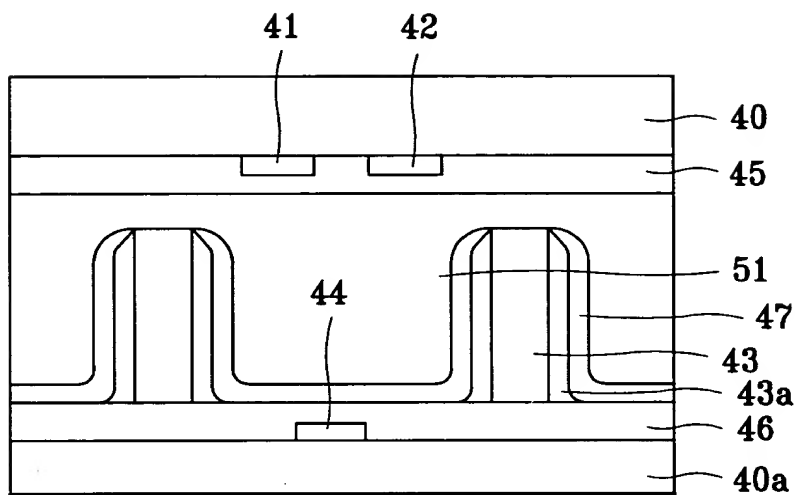


FIG.6

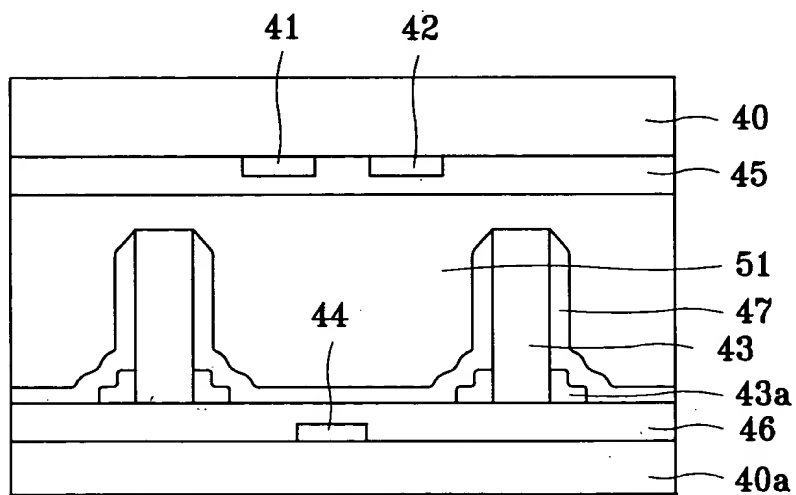


FIG.7a

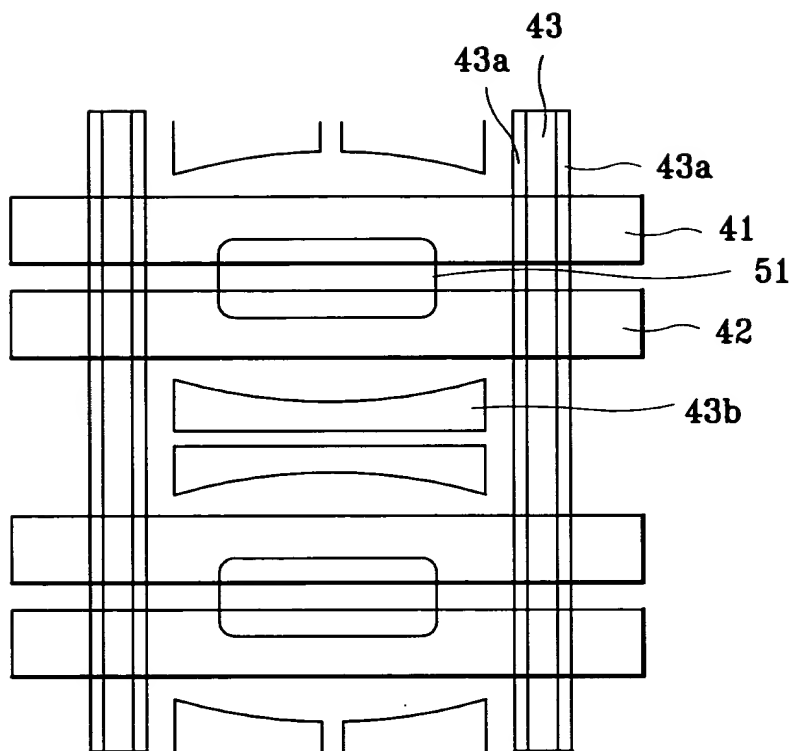


FIG.7b

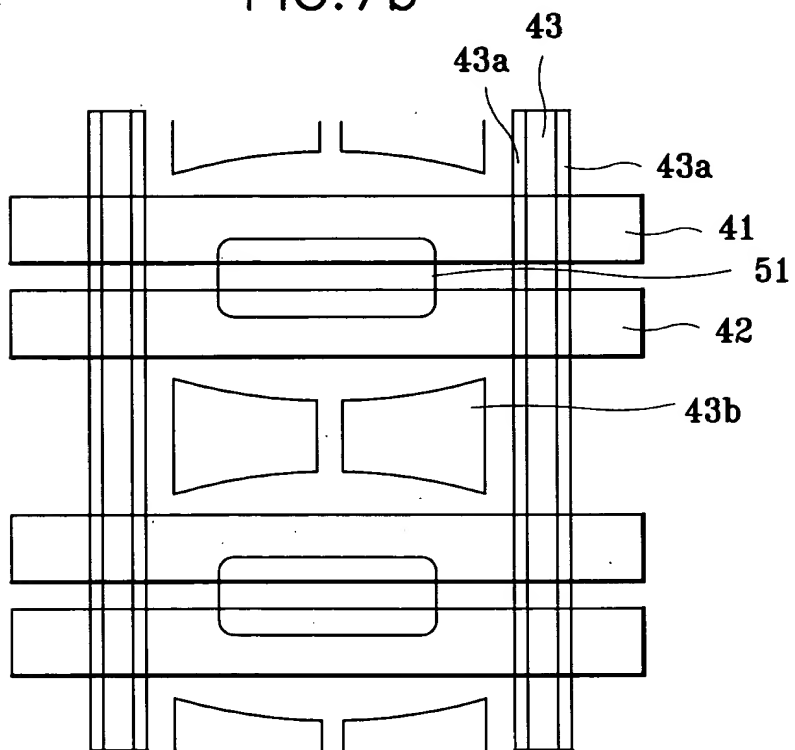
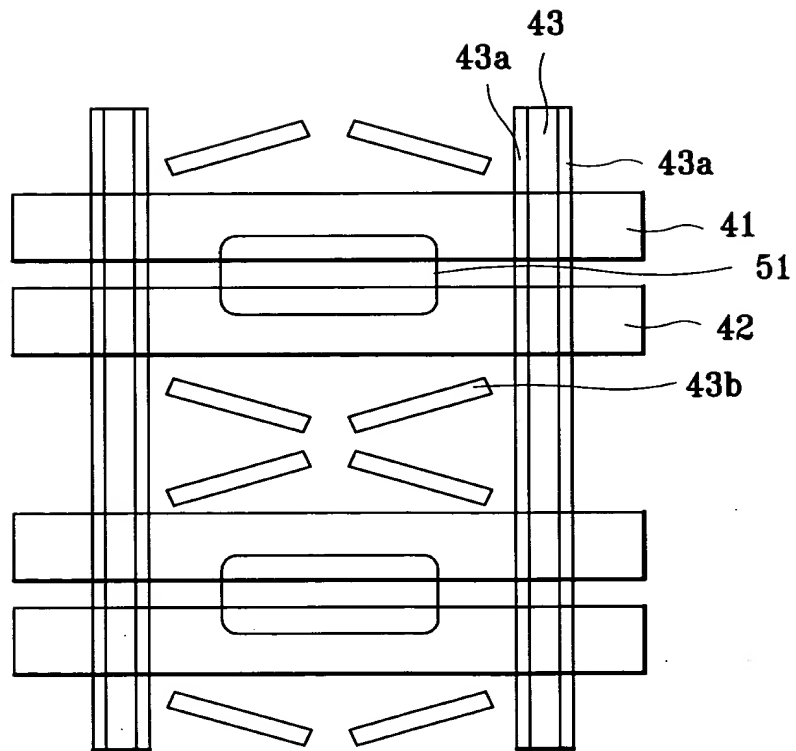


FIG.7c



A perspective view of a multi-layered electronic device assembly. The assembly consists of a top layer 110, a middle layer 111, and a bottom layer 112. A central channel 113 is formed within the middle layer 111. The channel 113 contains a series of vertical pillars 121. The pillars 121 are connected to a base layer 120. A layer 130 is positioned between the middle layer 111 and the bottom layer 112. Small rectangular components 122 are located at the bottom of the pillars 121.

FIG.9

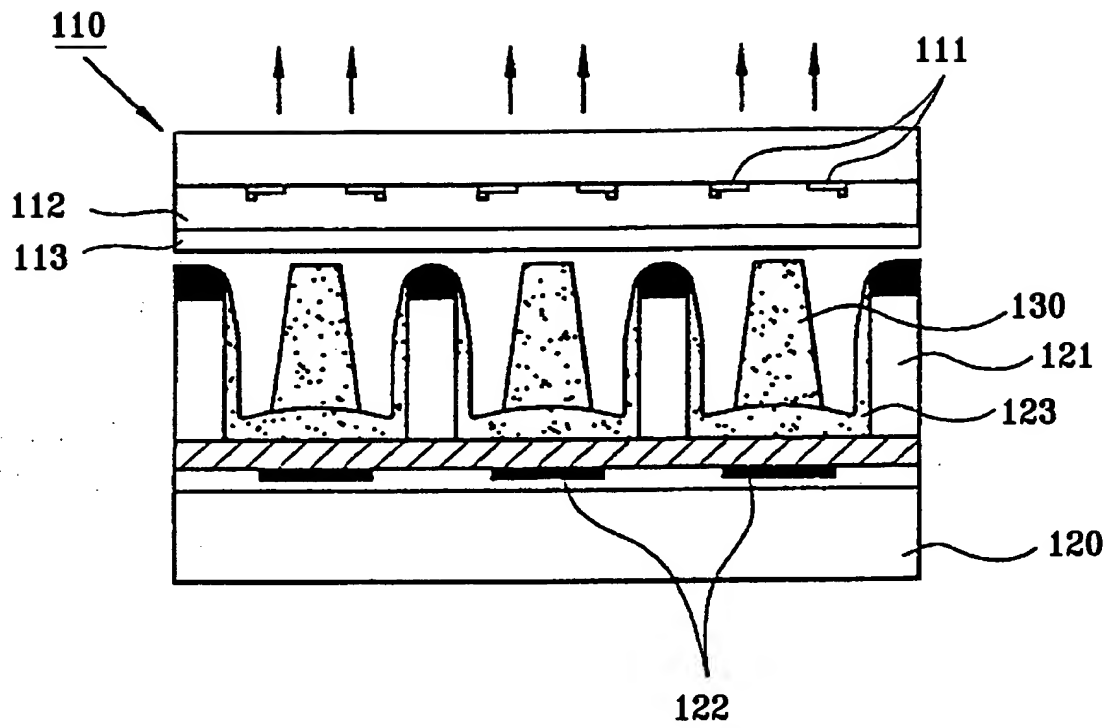
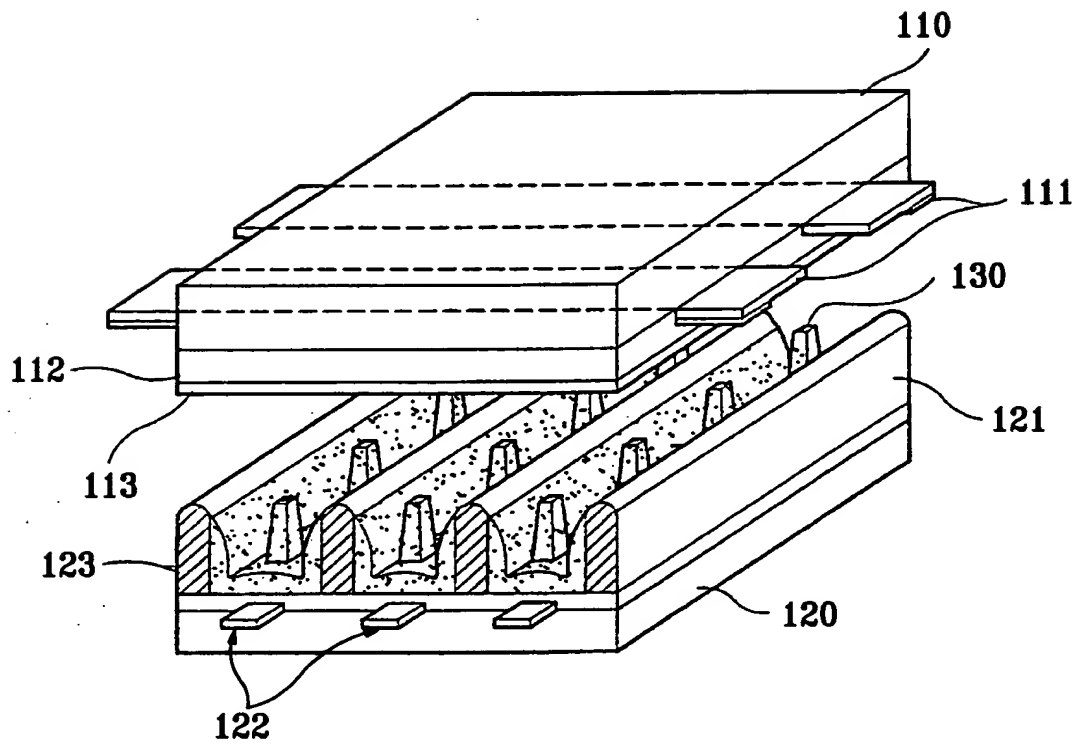




FIG.10



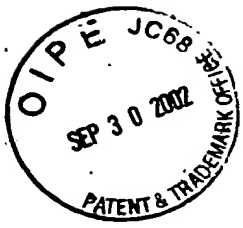


FIG.11

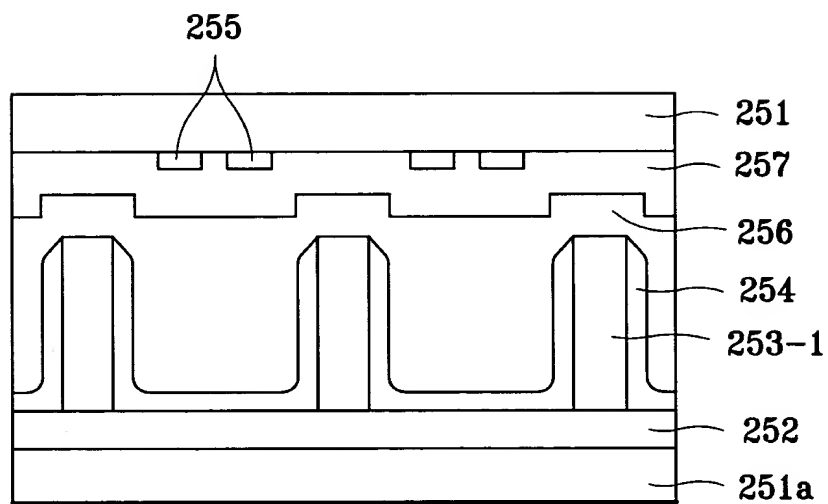


FIG.12

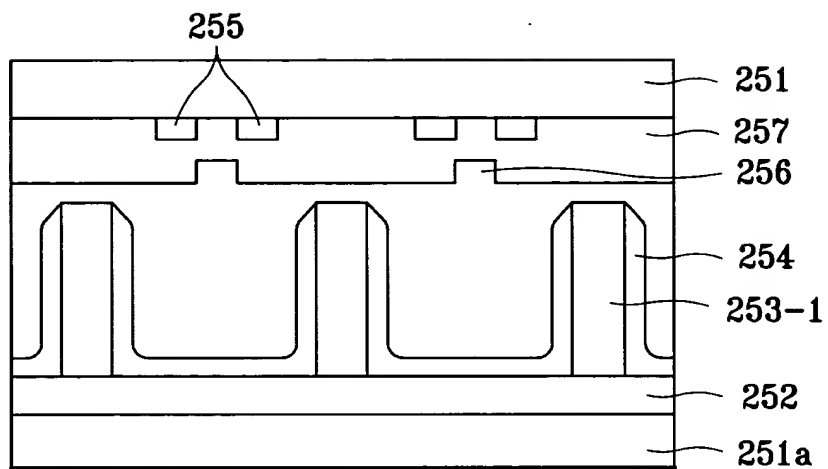
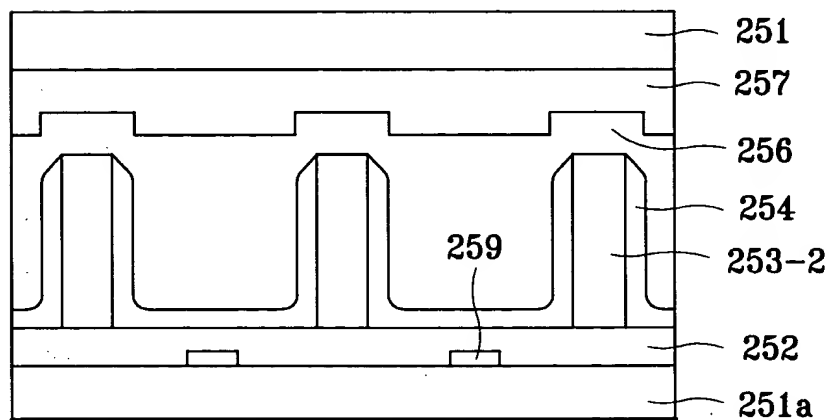
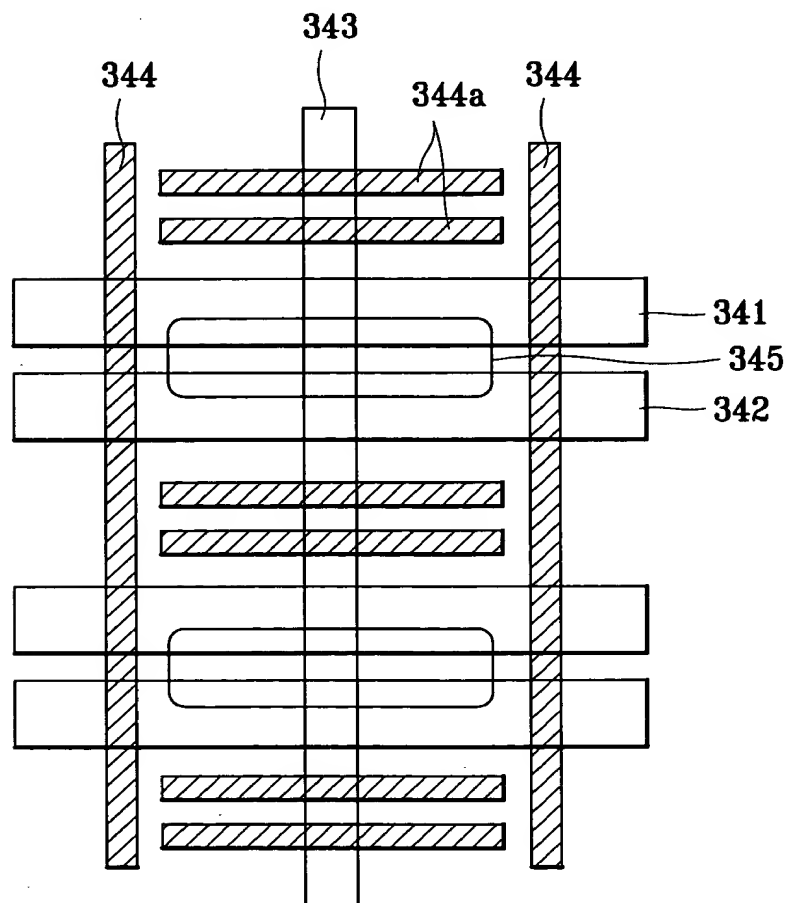


FIG.13





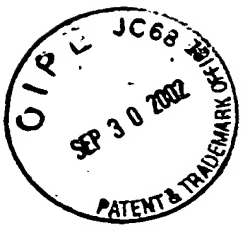


FIG.16

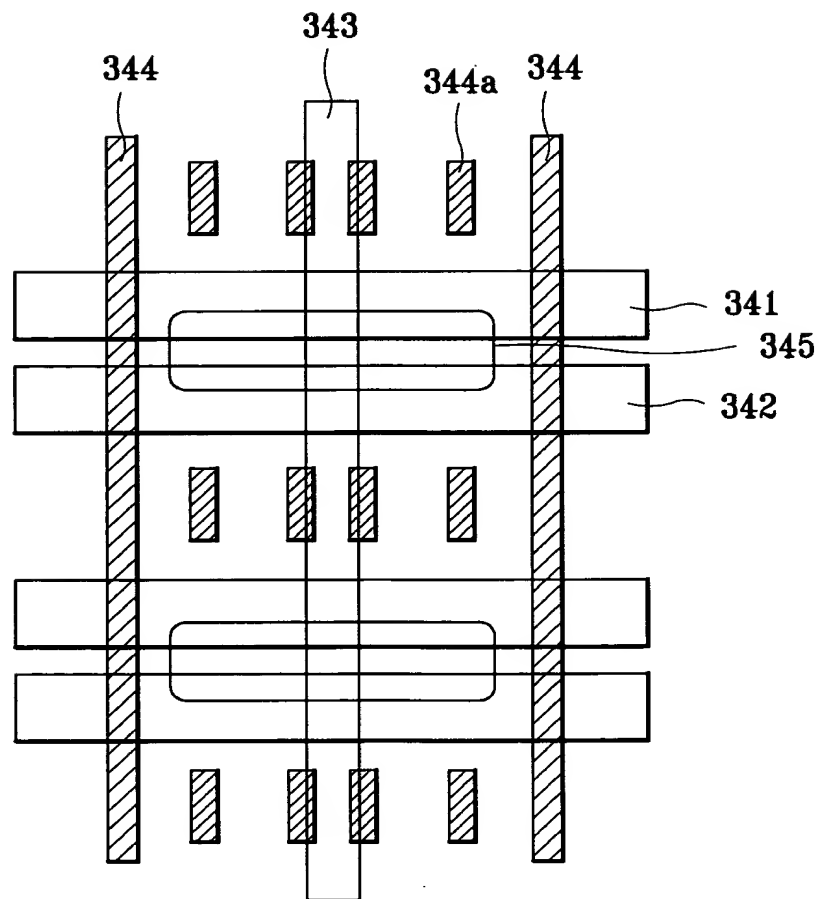


FIG.17

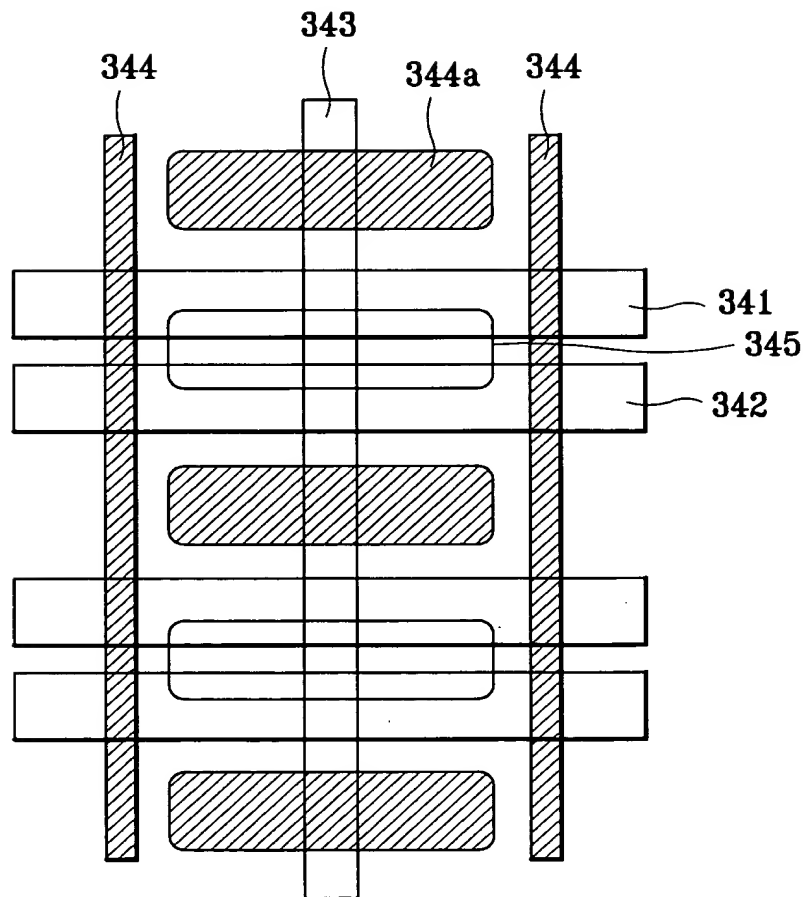


FIG. 18

